

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10830188			
<b>Filing Date:</b>	21-Apr-2004			
<b>Title of Invention:</b>	Method for accommodating small minimum die in wire bonded area array packages			
<b>First Named Inventor/Applicant Name:</b>	Ryan Lane			
<b>Filer:</b>	Larry Jan Moskowitz/Pam Ly/WMH			
<b>Attorney Docket Number:</b>	020378D1			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
Petition-revive unintent. abandoned appl	1453	1	1500	1500
<b>Patent-Appeals-and-Interference:</b>				
Filing a brief in support of an appeal	1402	1	500	500
<b>Post-Allowance-and-Post-Issuance:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				2000